PRESS RELEASE

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What's in the Apple Watch Series 6?

TechSearch International's teardown of the Apple Watch Series 6 GPS+LTE examined 108 board-level packages plus another 17 packages inside modules and found 27% more wafer level packages (WLPs) than in the previous Series 5, including packages in the wireless charger. Apple used more multi-die modules in the new watch.

X-ray images, shot on equipment provided by Creative Electron, offer a look inside the modules. Details about the die inside were revealed after decapsulation. An increasing number of flip chip die can be found, along with WLPs and some wire bond parts. Apple's S6 Application Processor continues to be packaged in TSMC's InFO fan-out WLP in a package-on-package format. A full deconstruction of the PoP was performed.

- All 38 packages encapsulated in the S6 module extracted *in whole*
- Construction analysis of fan-out package-on-package (PoP) use for processor and memory
- Cross-sections and laminate substrate metrics
- Metrics for all 156 die in the watch and charger provided

The latest teardown is a 117-page report and an accompanying set of 25 PowerPoint slides gives extra insight into the product.

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